CELCON® M270 ECO-B

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Celcon® acetal copolymer grade M270 is a lower molecular weight, high - flow grade designed for superior moldability in multi-cavity, intricate or hard to fill molds applications. Chemical abbreviation according to ISO 1043-1: POM Please also see Hostaform® C 27021.
ECO-B: Celcon® ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	23	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	1.7	%	ISO 294-4, 2577
Molding shrinkage, normal	1.6	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	406000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	9700	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Flexural modulus	399000	psi	ISO 178
Flexural stress at 3.5%	11000	psi	ISO 178
Compressive stress at 1% strain	4500	psi	ISO 604
Tensile creep modulus, 1h	334000	psi	ISO 899-1
Tensile creep modulus, 1000h	189000	psi	ISO 899-1
Charpy impact strength, 23°C	55.2	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	51.4	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	2.47	$ftlb/in^2$	ISO 179/1eA
Izod notched impact strength, 23°C	2.57	$ftlb/in^2$	ISO 180/1A
Izod notched impact strength, -30°C	2.38	$ftlb/in^2$	ISO 180/1A

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	217	°F	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	313	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.61	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.667	E-4/°F	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.75	%	Sim. to ISO 62
Water absorption, Immersion 24h	0.22	%	Sim. to ISO 62
Density	0.0509	lb/in³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	365	°F
Min. melt temperature	356	°F
Max. melt temperature	374	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	2h²-3	s
Back pressure	580	psi
Ejection temperature	284	°F

Characteristics

Processing	Injection Molding
Additives	Release agent
Special characteristics	High Flow
Sustainability	Bio-Content

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general

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purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

Processing Notes

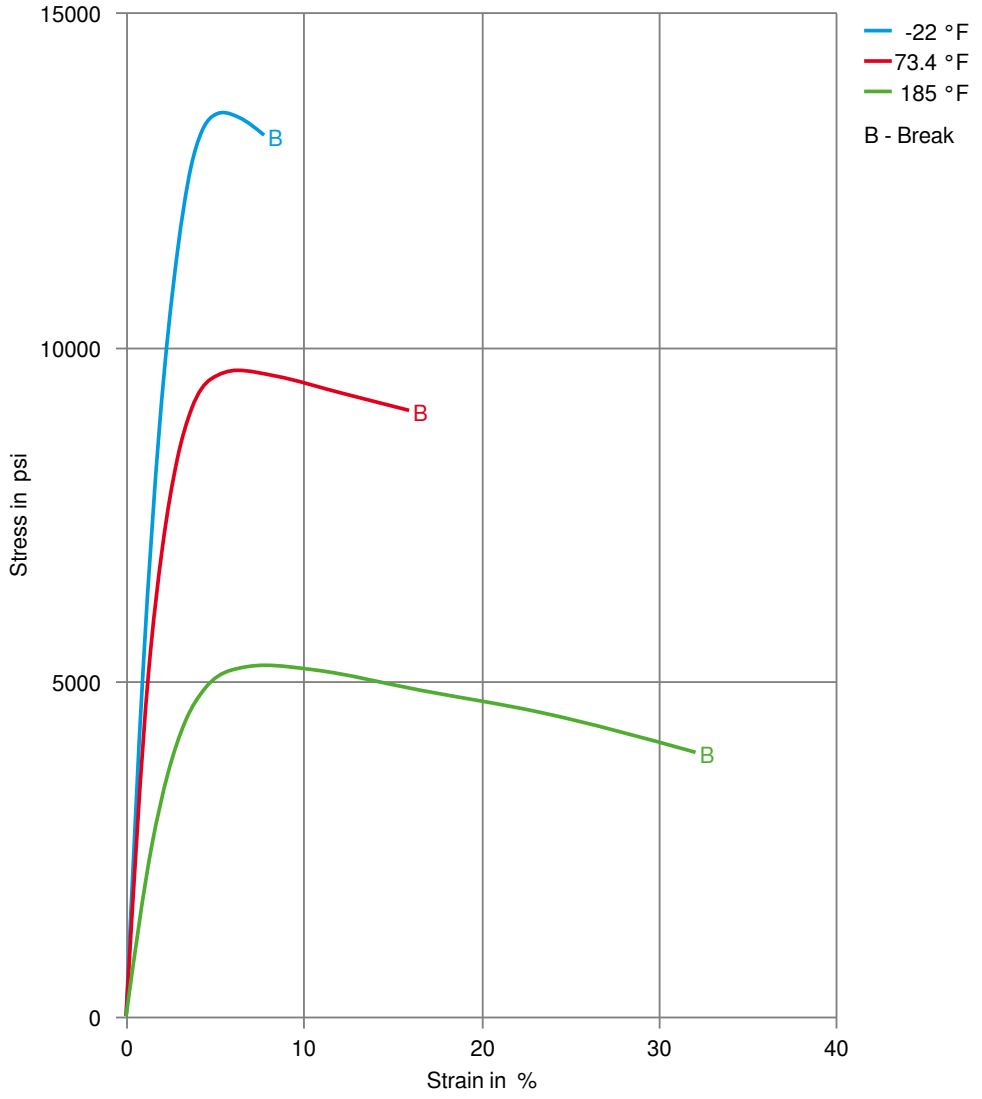
Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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Stress-strain

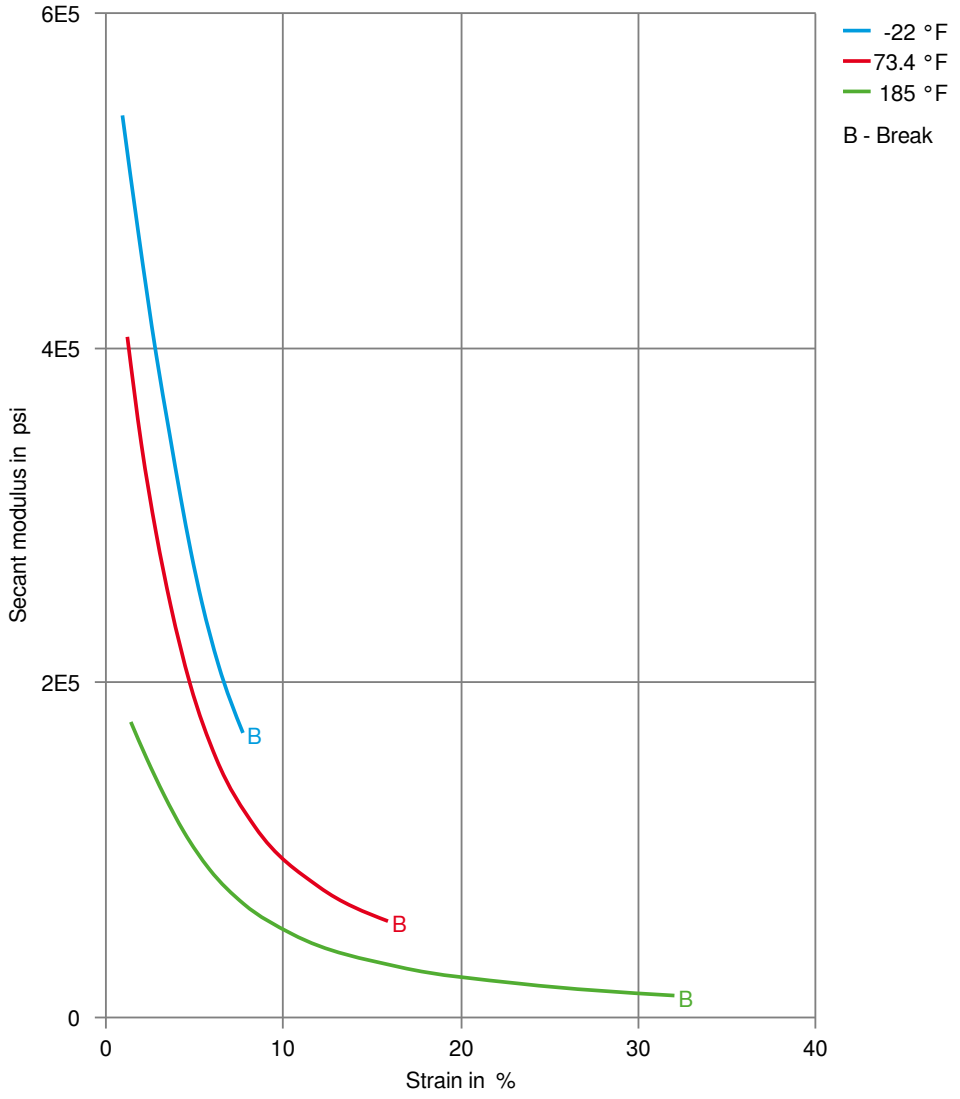


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Secant modulus-strain



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